![MICROCHIP logo]

SST39LF010/020/040 and SST39VF010/020/040
45 ns and B3KE EOL Supplemental Information

Description

The SST39LF010, SST39LF020, SST39LF040 and SST39VF010, SST39VF020, SST39VF040 are 128K x8, 256K x8 and 5124K x8 CMOS Multi-Purpose Flash (MPF) manufactured with SST's proprietary, high performance CMOS SuperFlash technology. The split-gate cell design and thick-oxide tunneling injector attain better reliability and manufacturability compared with alternate approaches. The SST39LF010/020/040 devices write (Program or Erase) with a 3.0-3.6V power supply. The SST39VF010/020/040 devices write with a 2.7-3.6V power supply. The devices conform to JEDEC standard pinouts for x8 memories.

This document provides supplemental information about the 45 ns and B3KE package parts which are End-of-Life (EOL). Except for the information provided herein, the EOL parts behave as described in the SST39LF010/020/040 and SST39VF010/020/040 data sheet DS-20005023. See page 3 for specific part numbers.
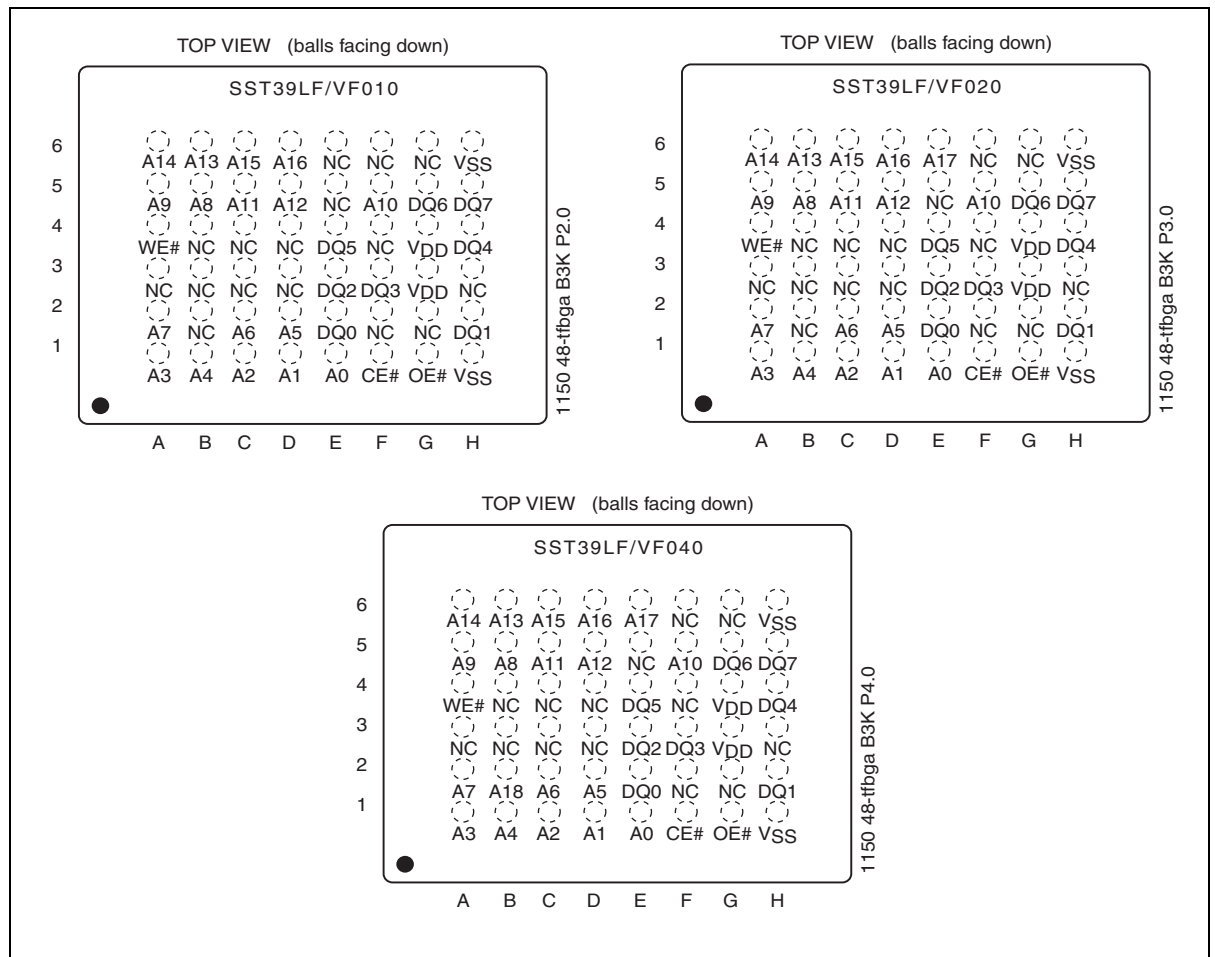
Pin Assignments

Figure 1: Pin Assignment for 48-ball TFBGA (6mm x 8mm) for 1 Mbit, 2 Mbit, and 4 Mbit

AC Characteristics

Table 1: Read Cycle Timing Parameters V_{DD} = 3.0-3.6V for SST39LF010/020/040

| Symbol | Parameter | SST39LF010-45 SST39LF020-45 SST39LF040-45 | | Units |
		Min	Max	
T_{RC}	Read Cycle Time	45		ns
T_{CE}	Chip Enable Access Time		45	ns
T_{AA}	Address Access Time		45	ns
T_{OE}	Output Enable Access Time		30	ns
T_{CLZ}[1]	CE# Low to Active Output	0		ns
T_{OLZ}[1]	OE# Low to Active Output	0		ns
T_{CHZ}[1]	CE# High to High-Z Output		15	ns
T_{OHZ}[1]	OE# High to High-Z Output		15	ns
T_{OH}[1]	Output Hold from Address Change	0		ns

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1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.
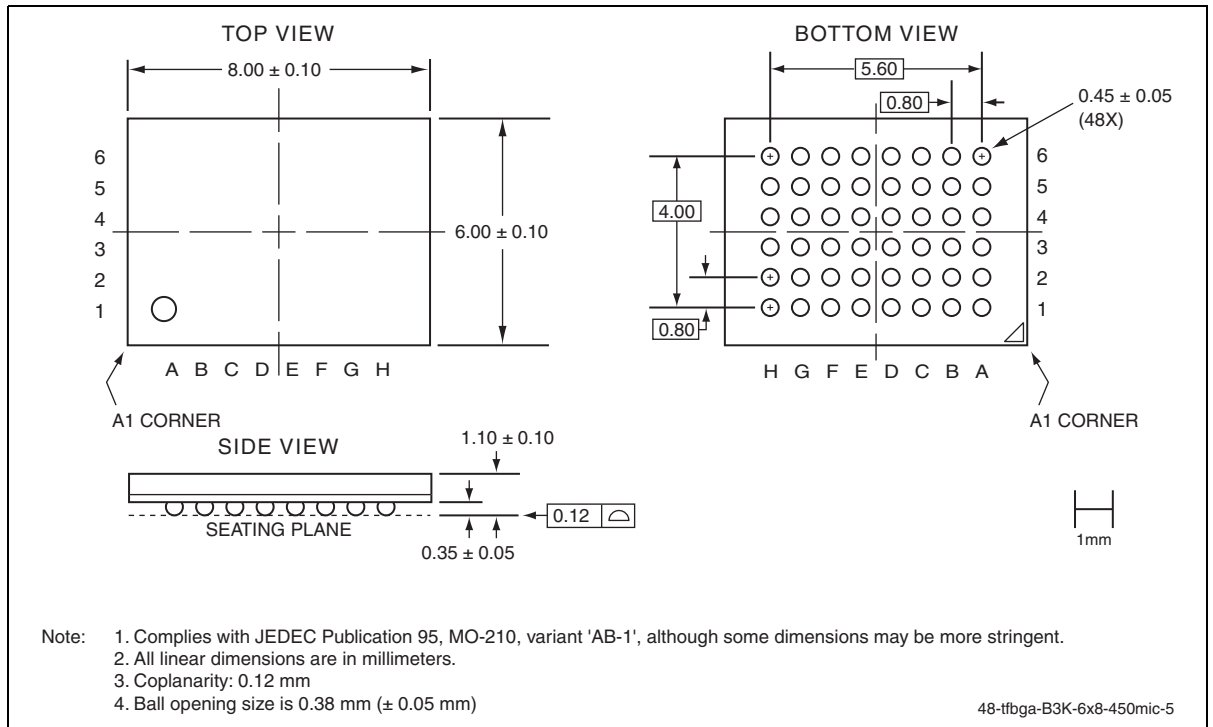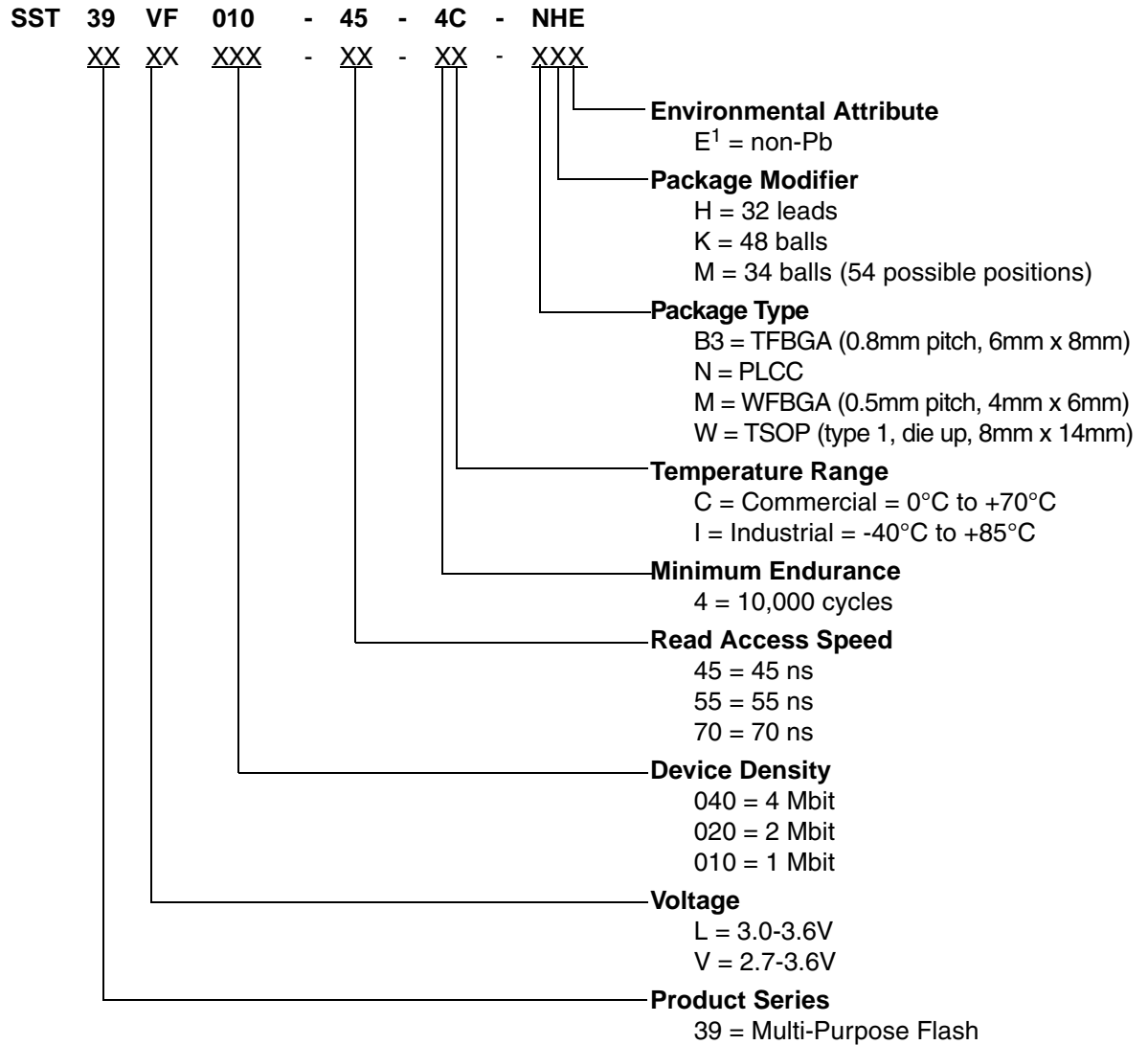
Packaging Diagram

Figure 2: 48-ball Thin-profile, Fine-pitch Ball Grid Array (TFBGA) 6mm x 8mm
SST Package Code: B3K

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SST39LF010/020/040 and SST39VF010/020/040
45 ns and B3KE EOL Suplemental Information

Product Ordering Information

SST 39 VF 010 - 45 - 4C - NHE
XX XX XXX - XX - XX - XXX

Environmental Attribute
E[1] = non-Pb

Package Modifier
H = 32 leads
K = 48 balls
M = 34 balls (54 possible positions)

Package Type
B3 = TFBGA (0.8mm pitch, 6mm x 8mm)
N = PLCC
M = WFBGA (0.5mm pitch, 4mm x 6mm)
W = TSOP (type 1, die up, 8mm x 14mm)

Temperature Range
C = Commercial = 0°C to +70°C
I = Industrial = -40°C to +85°C

Minimum Endurance
4 = 10,000 cycles

Read Access Speed
45 = 45 ns
55 = 55 ns
70 = 70 ns

Device Density
040 = 4 Mbit
020 = 2 Mbit
010 = 1 Mbit

Voltage
L = 3.0-3.6V
V = 2.7-3.6V

Product Series
39 = Multi-Purpose Flash

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1. Environmental suffix "E" denotes non-Pb solder. SST non-Pb solder devices are RoHS compliant.

EOL Data Sheet

Valid combinations for SST39LF010

SST39LF010-45-4C-NHE   SST39LF010-45-4C-WHE   SST39LF010-45-4C-B3KE
SST39LF010-45-4C-MME

Valid combinations for SST39VF010

SST39VF010-70-4C-B3KE

SST39VF010-70-4I-B3KE

Valid combinations for SST39LF020

SST39LF020-45-4C-NHE   SST39LF020-45-4C-WHE   SST39LF020-45-4C-B3KE
SST39LF020-45-4C-MME

Valid combinations for SST39VF020

SST39VF020-70-4C-B3KE

SST39VF020-70-4I-B3KE

Valid combinations for SST39LF040

SST39LF040-45-4C-NHE   SST39LF040-45-4C-WHE   SST39LF040-45-4C-B3KE

Valid combinations for SST39VF040

SST39VF040-70-4C-B3KE

SST39VF040-70-4I-B3KE

Note: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.

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Table 2: Revision History

Revision	Description	Date
A	• EOL document for 45 ns parts and B3KE parts	Jun 2013

Specifications are subject to change without notice. Refer to www.microchip.com for the most recent documentation. For the most current package drawings, please see the Packaging Specification located at http://www.microchip.com/packaging.

Memory sizes denote raw storage capacity; actual usable capacity may be less.

SST makes no warranty for the use of its products other than those expressly contained in the Standard Terms and Conditions of Sale.

For sales office locations and information, please see www.microchip.com.